

## **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. **(Withdrawn)** A bonding method in which an electronic component is connected via bumps to a substrate and the electronic component is then packaged on the substrate, comprising the steps of:

performing plasma processing on a surface of the substrate that packages the electronic component, a surface of the electronic component that is connected to the substrate, and a surface of the bumps;

heating the bumps to a temperature lower than a melting point of the bumps; and  
compression bonding the substrate and the electronic component via the bumps.

2. **(Withdrawn)** A bonding method according to claim 1, wherein ultrasonic waves are directed on the bumps when the substrate and the electronic component are being compression bonded via the bumps.

3. **(Currently Amended)** A bonding stage that packages an electronic component on a substrate, comprising:

a placement member, the placement member having a plasma generating electrode and an electrostatic adhesion electrode, and the placement member having a placement surface on which is placed the substrate or the electronic component; and

a supporting member that supports the placement member, wherein an aperture portion of the supporting member is joined in an airtight seal to the placement member, and a ceramic thermal insulation material is provided in an inner space of the supporting member such that the inner space is substantially filled with the ceramic thermal insulation material.

4. **(Currently Amended)** A bonding stage according to claim 3, wherein the placement member is provided with a heater electrode, and wherein the supporting member is cylindrical.

5. **(Canceled)**

6. **(Currently Amended)** A bonding stage according to claim [[5]] 3, wherein the ceramic thermal insulation material is an Al<sub>2</sub>O<sub>3</sub> - SiO<sub>2</sub> - CaO - Li<sub>2</sub>O based ceramic thermal insulation material.

7. **(Currently Amended)** A bonding stage according to claim [[5]] 3, wherein the supporting member is formed from stainless steel or an Fe-Ni-Co based alloy.

8. **(Currently Amended)** A bonding stage according to claim [[5]] 3, wherein the placement member is joined to the supporting member via an O-ring or a metal gasket.

9. **(Currently Amended)** An electronic component packaging apparatus comprising:

the bonding stage according to claim [[5]] 3;  
a bonding tool positioned above the bonding stage; and  
a chamber that houses the bonding stage and the bonding tool.

10. **(Original)** A electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with an electrostatic adhesion mechanism that electrostatically holds the substrate or the electronic component.

11. **(Original)** A electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with at least one of a plasma generating electrode and a heater electrode.

**12. (Original)** A electronic component packaging apparatus according to claim 9, further comprising a pressure application mechanism that applies pressure to the bonding tool.

**13. (Original)** An electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with an ultrasonic device that emits ultrasonic waves.